

BB02-RG :-2.0mm x 2.0mm (0.079" x 0.79") SOCKET, STRAIGHT, SMD, DUAL ROW - 04 to 80 CONTACTS LOW PROFILE:2.2mm, DUAL ENTRY

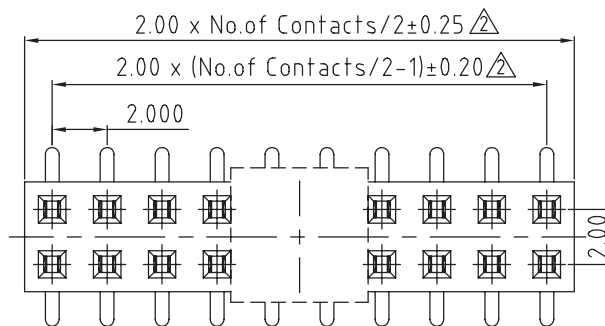
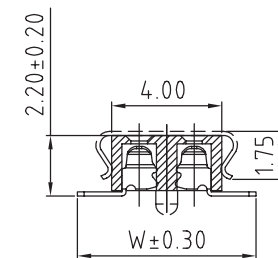
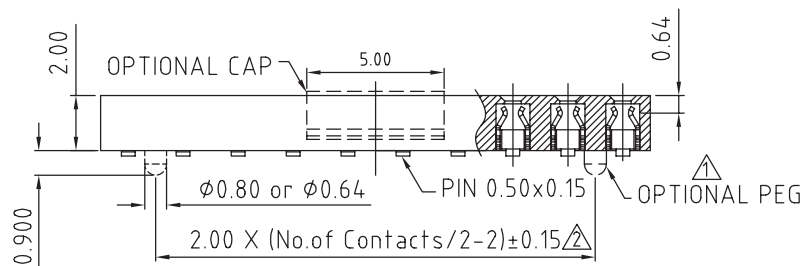
## SPECIFICATIONS

CURRENT RATING	2 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACT RESISTANCE	20m ohms MAX.
DIELECTRIC WITHSTANDING	AC 500 V
OPERATING TEMPREATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD: NYLON 6T
PLATING	GOLD OR TIN OVER 30-50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC MANUAL SOLDER: 350°C FOR 3-5 SEC

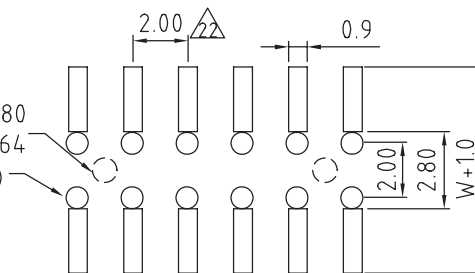
## NOTES:

1. RECOMMANDED MATING PIN LENGTH FOR TOP ENTRY: 1.5MM.  $\triangle$ 

MATES WITH:	BB02-FA	BB02-FS	BB02-RN
	BB02-FD	BB02-FU	
	BB02-FE	BB02-FW	
	BB02-FG	BB02-FY	
	BB02-FP	BB02-FZ	
	BB02-FQ	BB02-RH	



$\phi 1.00$  for Peg  $\phi 0.80$   
 $\phi 0.84$  for Peg  $\phi 0.64$   
 $\phi 0.80$  REF.



BOTTOM ENTRY TYPE  
RECOMMENDED PC BOARD LAYOUT  
(TOLERANCE: ±0.05)

## HOW TO ORDER

BB02 - RGXX2 - XXX - XXXXXXX

NO. OF CONTACTS  
 $\triangle$  04 TO 80  
(MIN. 06 FOR W/PEG)

$\triangle$  FOOTPRINT  
"W" OPTION  
0 = 6.5MM  
A = 5.3MM

PACKAGING OPTIONS  
3 - TUBE  
 $\triangle$  4 - TUBE & FILM  
5 - TUBE & CAP  
6 - T & R  
 $\triangle$  7 - T & R & FILM  
8 - T & R & CAP

$\triangle$  LOCATING PEG OPTION  
A = WITH PEG  $\phi 0.80$   
B = WITHOUT PEG  
 $\triangle$  C = WITH PEG  $\phi 0.64$

CONTACT PLATING OPTIONS  $\triangle$   $\triangle$   $\triangle$ 

K = GOLD FLASH (STANDARD)

A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL

B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL

C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL

T = BRIGHT TIN

M = MATT TIN

TOP ENTRY TYPE  
RECOMMENDED PC BOARD LAYOUT  
 $\triangle$  (TOLERANCE: ±0.05)

REV.	DATE & DRN
10	12/05/05 - NYW RELEASE
11	30/05/06 - NYW
12	ADD PEG OPTION 4 & 7.
13	MIN. CONTACT NO 06=04.
14	06/06/06 - NYW
15	AMEND DIMENSIONS.
16	08/08/06 - NYW
17	DRAWING MODIFICATION.
18	02/10/06 - CHC
19	REMOVE SELECTIVE GOLD
20	31/05/07 - NYW
21	ADD NOTES 1.
22	ADD FOOTPRINT W OPTION.
23	25/07/07 - CHC
24	ADD SELECTIVE GOLD
25	16/10/07 - CHC
26	REMOVE SELECTIVE GOLD
27	CONTACT PLATING.
28	18/01/08 - NYW
29	PLATING MODIFICATION.
30	04/03/08 - CHC
31	ADD PEG OPTION C.
32	10/03/08 - CHC
33	ADD TOLERANCE OF PCB
34	LAYOUT.
35	31/12/08 - NYW
36	DRAWING MODIFICATION.
37	23/03/10 - NYW
38	AMEND PCB LAYOUT.

Scale:	5:1	THIRD ANGLE	Unstated Tolerances: X. ± 0.30 X. ± 0.25 XX ± 0.15 XXX ± 0.10	Material	SEE NOTE
Drawn:	CHC				
App'd:	XXXX	Title	SOCKET	NOT TO SCALE	
Date:	23 MAR '10	Revision:	2.2	Unit:	mm



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Type: BB02-RG

BB02-RG

Drawing Number:

Sheet 1 of 1

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